

ABSTRACT OF THE DISCLOSURE

A printed circuit board (PCB) substrate and method for construction of the same. In one embodiment, a first dielectric material is associated with a first current return layer and a second dielectric material is associated with a second current return layer. A signal path layer is interposed between the first dielectric material and the second dielectric material. An adhesive layer is interposed between the first dielectric material and the second dielectric material such that the adhesive layer is substantially coplanar relative to the signal path layer.